深圳市多迈电子有限公司 06 110 慢断系列

Description

06 110 Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Features

- High inrush current withstanding capability
- AEC-Q200 Automotive Grade Certified
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

Specifications

Electrical Characteristics			
Rated Current	1.0In	2.0In	2.5In
1A~8A	4 hour minimum	1~60 sec	5 sec maximum

Part No.	Rated Voltage	Rated Current (A)	Breaking Capacity (A) [1]	Typical Cold. Resistance (mOhms) [2]		Typical Voltage Drop (mV)	Typical Pre-Arcing I^2t (A^2Sec) [3]	Alpha Mark
	DC			Min	Max			
06 110 1	32V	1	50A	230	380	345	0.011	B/H
06 110 1.5		1.5	50A	115	185	270	0.045	H
06 110 2		2	50A	59	96	160	0.115	K
06 110 2.5		2.5	50A	38	68	145	0.14	L
06 110 3		3	50A	25	45	130	0.28	O
06 110 3.5		3.5	50A	17	31	130	0.5	R
06 110 4		4	50A	15	28	120	0.6	S
06 110 5		5	50A	8	18	110	1.9	T
06 110 6		6	50A	5.5	13	110	2.3	V**
06 110 7		7	50A	5	12	90	3.0	X**
06 110 8		8	50A	4	7.5	80	4.5	Z**

* DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees

* Typical Pre-arching I^2t are measured at 10In Current

Choice fuse for surge application (USB charger etc.), make sure the I^2t of fuse is 4 times than surge.

**Different with other ratings, the color of glass cover of 6A, 7A and 8A is BLUE color

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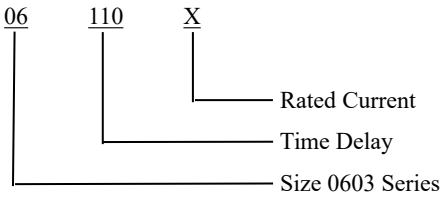
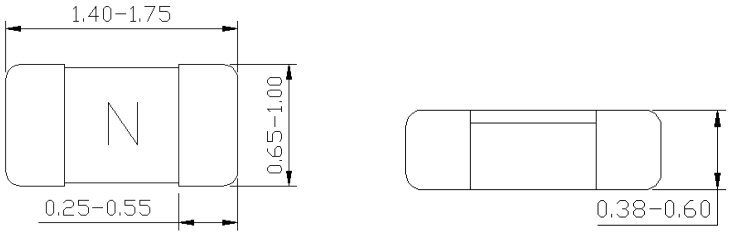
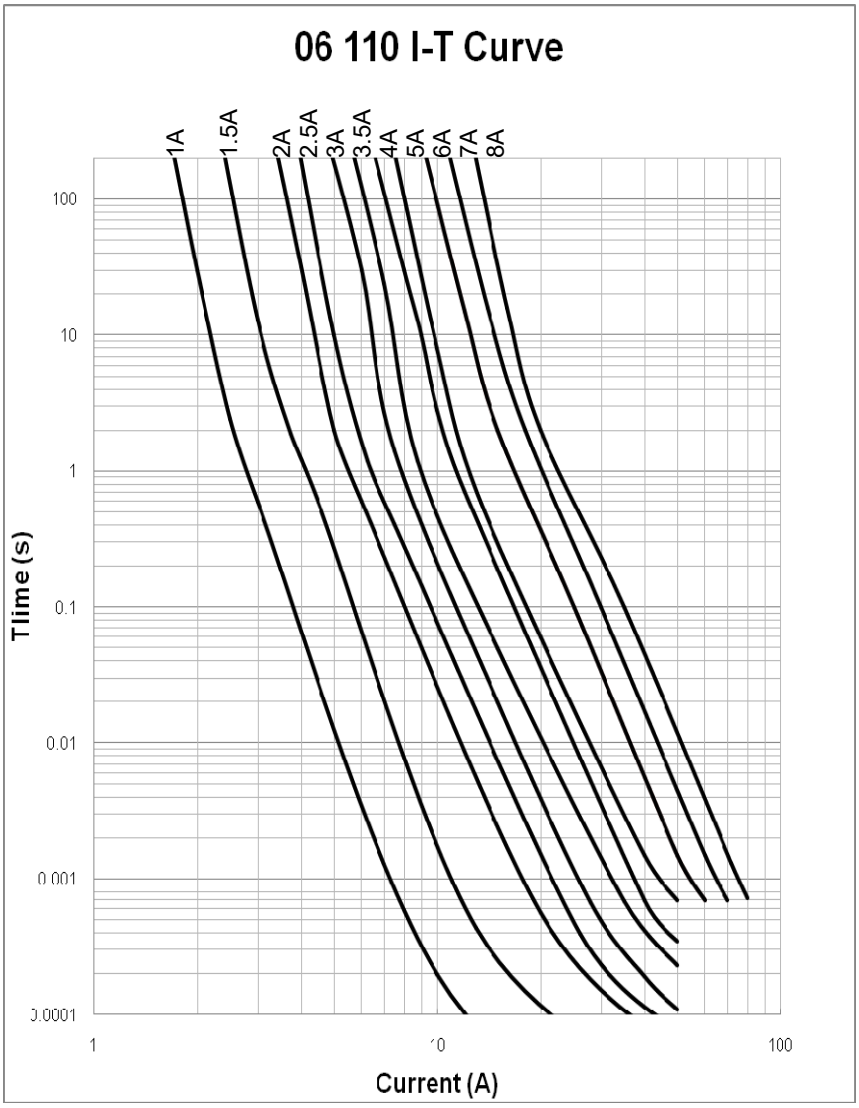
*Part No. Description

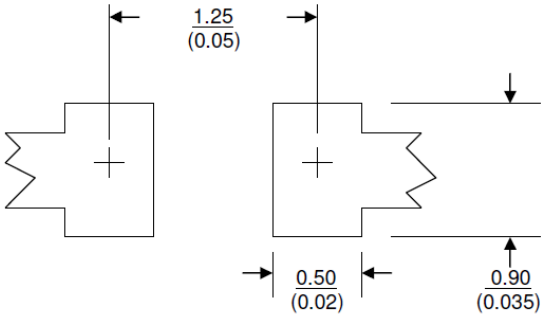


Dimension Drawing not to scale (Unit: mm)





Recommended land pattern



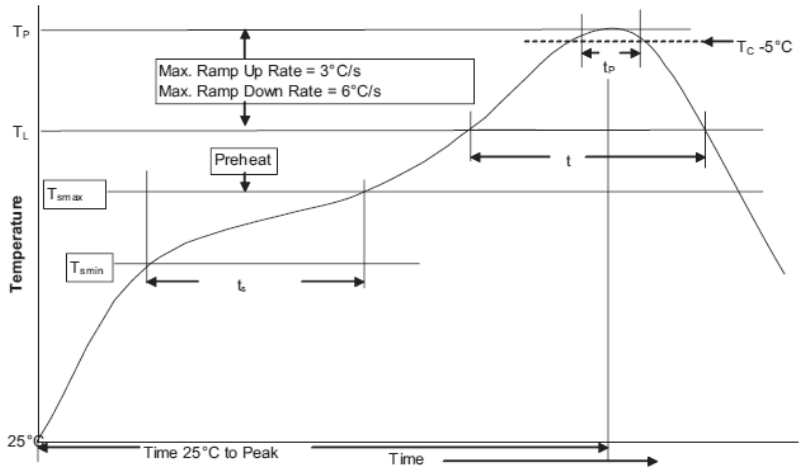
Unit: mm/inches

Soldering method

- Wave solder
  - Reservoir temperature: 260℃
  - Time in reservoir: 10 seconds maximum
- Infrared reflow

- Temperature: 260℃
- Time: 30 seconds maximum

Solder reflow profile

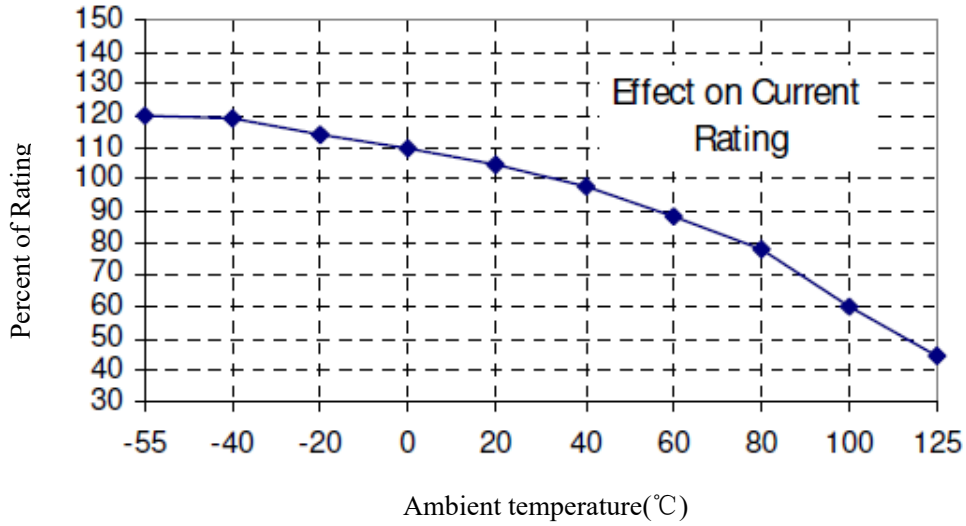


Profile Feature		Lead(Pb) free solder
Preheat and soak	• Temperature min.(T_{smin})	150℃
	• Temperature max. (T_{smax})	200℃
	• Time (T_{smin} to T_{smax}) (t_S)	60 - 120 Seconds
Average ramp up rate T_{smax} to T_p		3℃ / Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		217℃ 60 - 150 Seconds
Peak package body temperature (T_P)		260℃
Time (t_P) within 5℃ of the specified classification temperature (T_C)		30 Seconds
Average ramp-down rate (T_P to T_{smax})		6℃ / Second Max.
Time (25℃ to Peak Temperature)		8 Minutes Max.

Temperature Derating Curve

Normal ambient temperature: 23+/-3℃

Operating temperature: -55 ~ 125℃, with proper correction factor applied



Environmental Characteristics

Storage Conditions ……+40 °C Max. 70% RH Max. Packed in original packaging.

Agency Approvals

- Agency Approvals：UL、CSA
- Regulation/Standard: RoHS, Reach

Package information

Model	Q'ty/Reel
06 110 X	5000 pcs

Note: Reel packaging per EIA-481-1 standard